

Product Change Notification

Notification Date: May 29, 2015

**Product Change Notification
Number:** 1067

Affected Part Numbers: See Attachment I

Description of Change: Change the solder paste from SnAg to SnAgCu.

Change Identification: Date code 1532 and later.

Reason for Change: Increase the retention force of the surface mount components.

Expected Impact: This change will not impact the product form, fit, function, quality, or reliability.

Implementation of Change: August 3, 2015

Cessation of Present Process: August 3, 2015

Assessment: Qualification report and samples are available upon request.

Product Change Notification Authorization:

A handwritten signature in blue ink, appearing to read 'Mike King', with a stylized, cursive script.

Mike King
Product Engineering Manager
Optoelectronics Business Unit

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Customer Product Change Notification Acknowledgement:

Recipient Signature: _____

Printed Name: _____

Company: _____

Position: _____

Date: _____

Customer Product Change Acceptance:

Acceptance Signature: _____

Printed Name: _____

Company: _____

Position: _____

Date: _____

Please return this product change notification with signature to:

Jeff Beatty
1645 Wallace Drive
Carrollton, TX 75006
Phone: +1.972.323.2464
Fax: +1.972.389.2355
Email: jeff.beatty@ttelectronics.com

For any requests or exceptions, please contact your local TT Electronics sales representative

Product Change Notification

Attachment I
PCN 1067
Standard Part Number List

Part Number

OPA729G
OPA729R
OPA729W
OPA730W
OPA730Y
OPA731R
OPA731W
OPA733B
OPA733G
OPA733R
OPA733W
OPA733Y
OPA739B
OPA739G
OPA739R
OPA739W
OPA740B23
OPA740R23
OPA740W23
OPA741W23
OPA742B23
OPA742G23
OPA742R23
OPA742W23
OPA742Y23
OPA776
OPA779D-1169
OPA779D-610
OPA779S-240